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IDENTIFIER:

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Method for reducing microloading in an etchback of spin-on-glass or
polymer

TITLE - TI (1):

Method for reducing microloading in an etchback of spin-on-glass or polymer

Detailed Description Text - DETX (12):

The process of the invention results in excellent planarization and uniformity of an interlevel dielectric layer with significantly reduced microloading effect at the spin-on-glass etchback step and elimination of keyhole defects. The addition of O._{sub.2} to the etchback plasma is much more than the extra release of oxygen when the first oxide layer is exposed; therefore, the microloading effect of the extra release of oxygen is greatly reduced by the process of the invention.